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Understanding Embedded - Microprocessors

Embedded microprocessors are specialized computing chips designed to perform specific tasks within an embedded system. Unlike general-purpose microprocessors found in personal computers, embedded microprocessors are tailored for dedicated functions within larger systems, offering optimized performance, efficiency, and reliability. These microprocessors are integral to the operation of countless electronic devices, providing the computational power necessary for controlling processes, handling data, and managing communications.

Applications of Embedded - Microprocessors

Embedded microprocessors are utilized across a broad spectrum of applications, making them indispensable in

Details	
Product Status	Obsolete
Core Processor	MIPS-I
Number of Cores/Bus Width	1 Core, 32-Bit
Speed	20MHz
Co-Processors/DSP	System Control; CP0
RAM Controllers	DRAM
Graphics Acceleration	No
Display & Interface Controllers	-
Ethernet	-
SATA	-
USB	-
Voltage - I/O	5.0V
Operating Temperature	0°C ~ 85°C (TC)
Security Features	-
Package / Case	100-LQFP
Supplier Device Package	100-TQFP (14x14)
Purchase URL	https://www.e-xfl.com/product-detail/renesas-electronics-america/idt79r3041-20pf8

System Control Co-Processor

The R3041 also integrates on-chip a System Control Co-processor, CP0. CP0 manages the exception handling capability of the R3041, the virtual to physical address mapping of the R3041, and the programmable bus interface capabilities of the R3041. These topics are discussed in subsequent sections.

The R3041 does not include the optional TLB found in other members of the RISController family, but instead performs the same virtual to physical address mapping of the base version of the RISController family. These devices still support distinct kernel and user mode operation, but do not require page management software or an on-chip TLB, leading to a simpler software model and a lower-cost processor.

The memory mapping used by these devices is illustrated in Figure 3. Note that the reserved address spaces shown are for compatibility with future family members; in the current family members, references to these addresses are translated in the same fashion as their respective segments, with no traps or exceptions taken.

When using the base versions of the architecture, the system designer can implement a distinction between the user tasks and the kernel tasks, without having to execute page management software. This distinction can take the form of physical memory protection, accomplished by address decoding, or in other system specific forms. In systems which do not wish to implement memory protection, and wish to have the kernel and user tasks operate out of a single unified memory space, upper address lines can be ignored by the address decoder, and thus all references will be seen in the lower gigabyte of the physical address space.

The R3041 adds additional resources into the on-chip CP0. These resources are detailed in the R3041 User's Manual. They allow kernel software to directly control activity of the processor internal resources and bus interface, and include:

- **Cache Configuration Register:** This register controls the data cache block size and miss refill algorithm.
- **Bus Control Register:** This register controls the behavior of the various bus interface signals.
- **Count and Compare Registers:** Together, these two registers implement a programmable 24-bit timer, which can be used for DRAM refresh or as a general purpose timer.
- **Port Size Control Register:** This register allows the kernel to indicate the port width of reads and writes to various sub-regions of the physical address space. Thus, the R3041 can interface directly with 8-, 16-, and 32-bit memory ports, including a mix of sizes, for both instruction and data references, without requiring additional external logic.

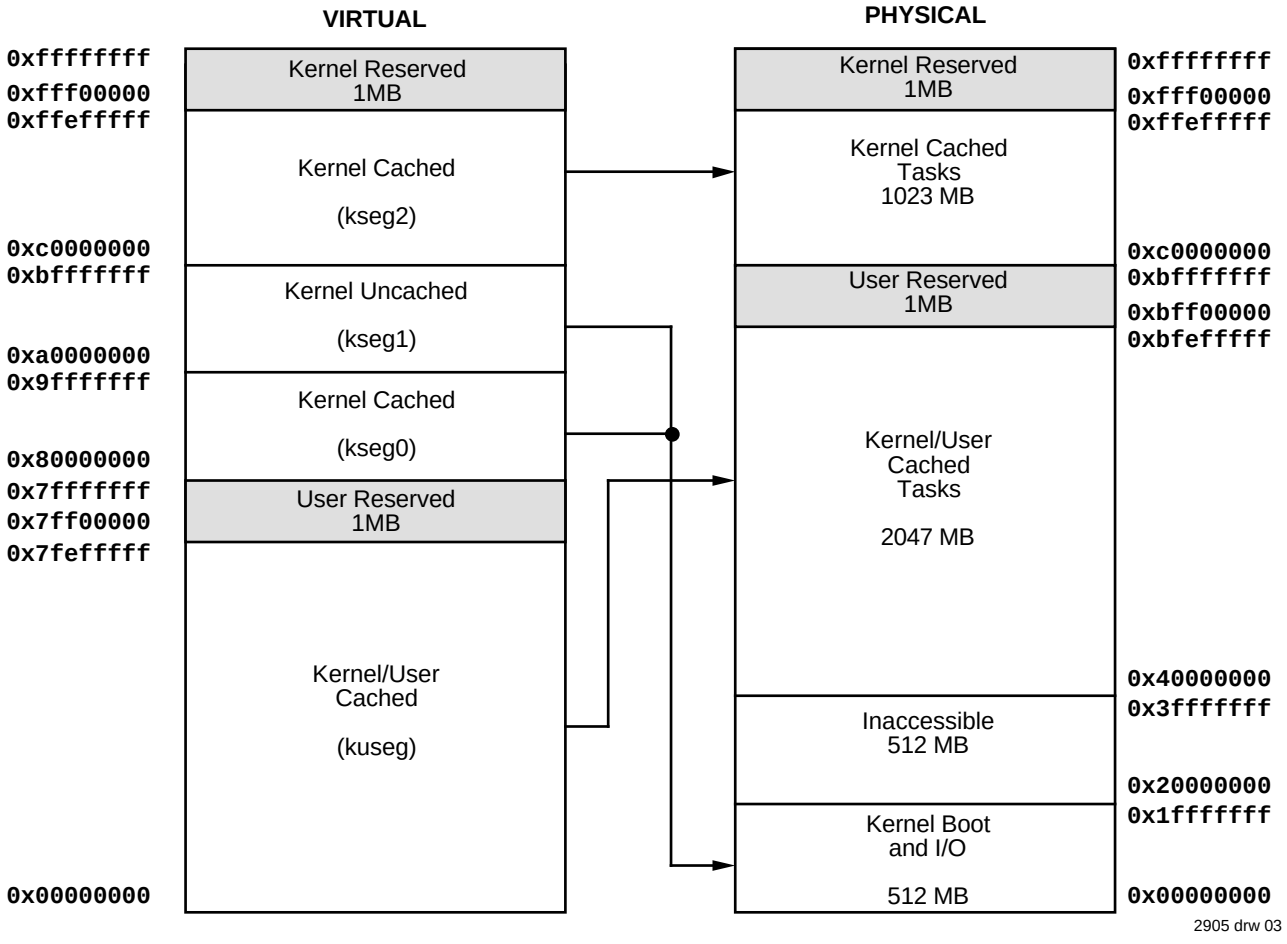


Figure 3. Virtual to Physical Mapping of Base Architecture Versions

DEVELOPMENT SUPPORT

The IDT RISController family is supported by a rich set of development tools, ranging from system simulation tools through PROM monitor and debug support, applications software and utility libraries, logic analysis tools, and sub-system modules.

Figure 5 is an overview of the system development process typically used when developing R3041 applications. The RISController family is supported in all phases of project development. These tools allow timely, parallel development of hardware and software for RISController family based applications, and include tools such as:

- Optimizing compilers from MIPS Technology, the acknowledged leader in optimizing compiler technology.
- Cross development tools, available in a variety of development environments.
- The high-performance IDT floating point emulation library software.
- The IDT Evaluation Board, which includes RAM, EPROM, I/O, and the IDT PROM Monitor.
- IDT Laser Printer System boards, which directly drive a low-cost print engine, and runs Adobe PostScript™ Page Description Language
- Adobe PostScript Page Description Language running on the IDT RISController family.
- The IDT/sim™ PROM Monitor, which implements a full PROM monitor (diagnostics, remote debug support, peek/

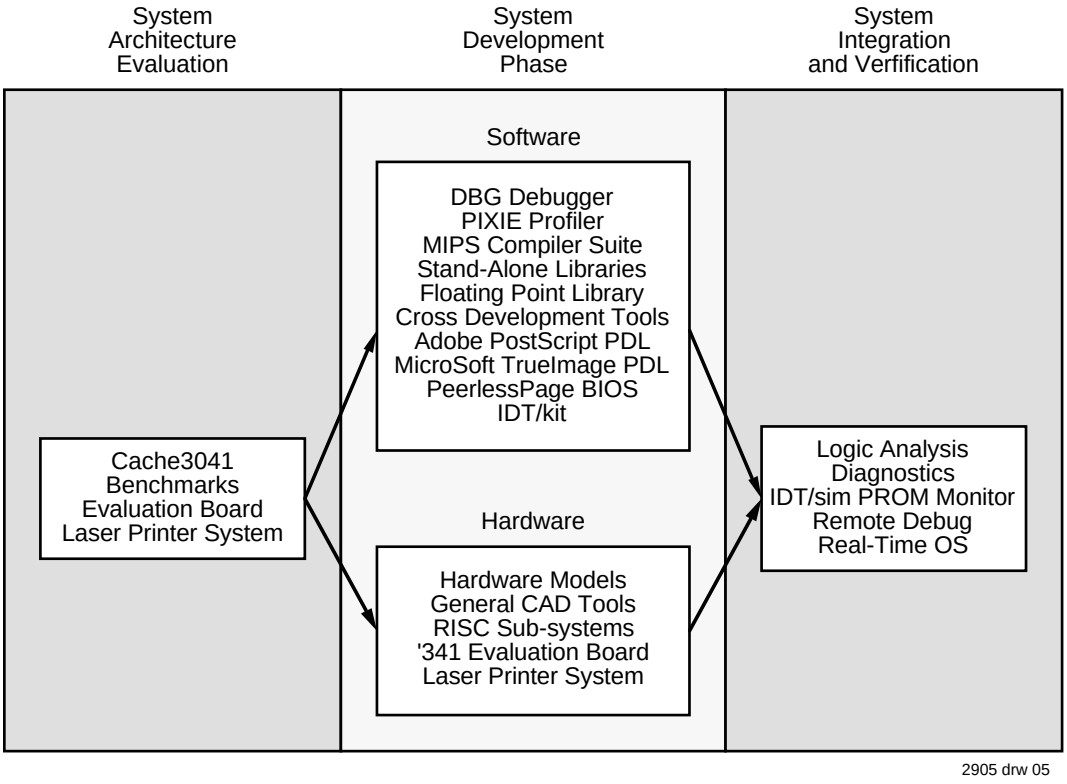
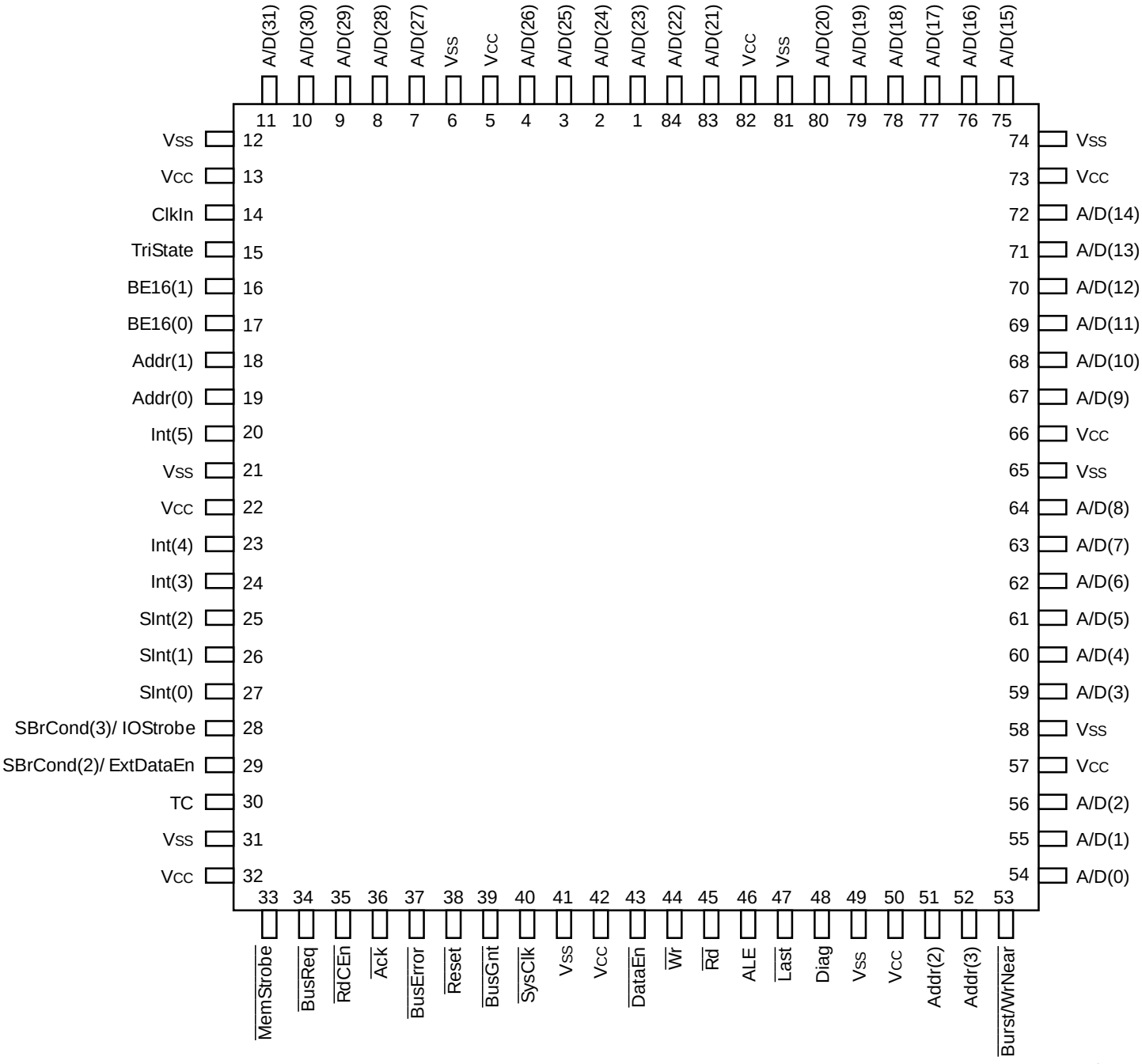


Figure 5. R3041 Development Environment

PIN CONFIGURATIONS

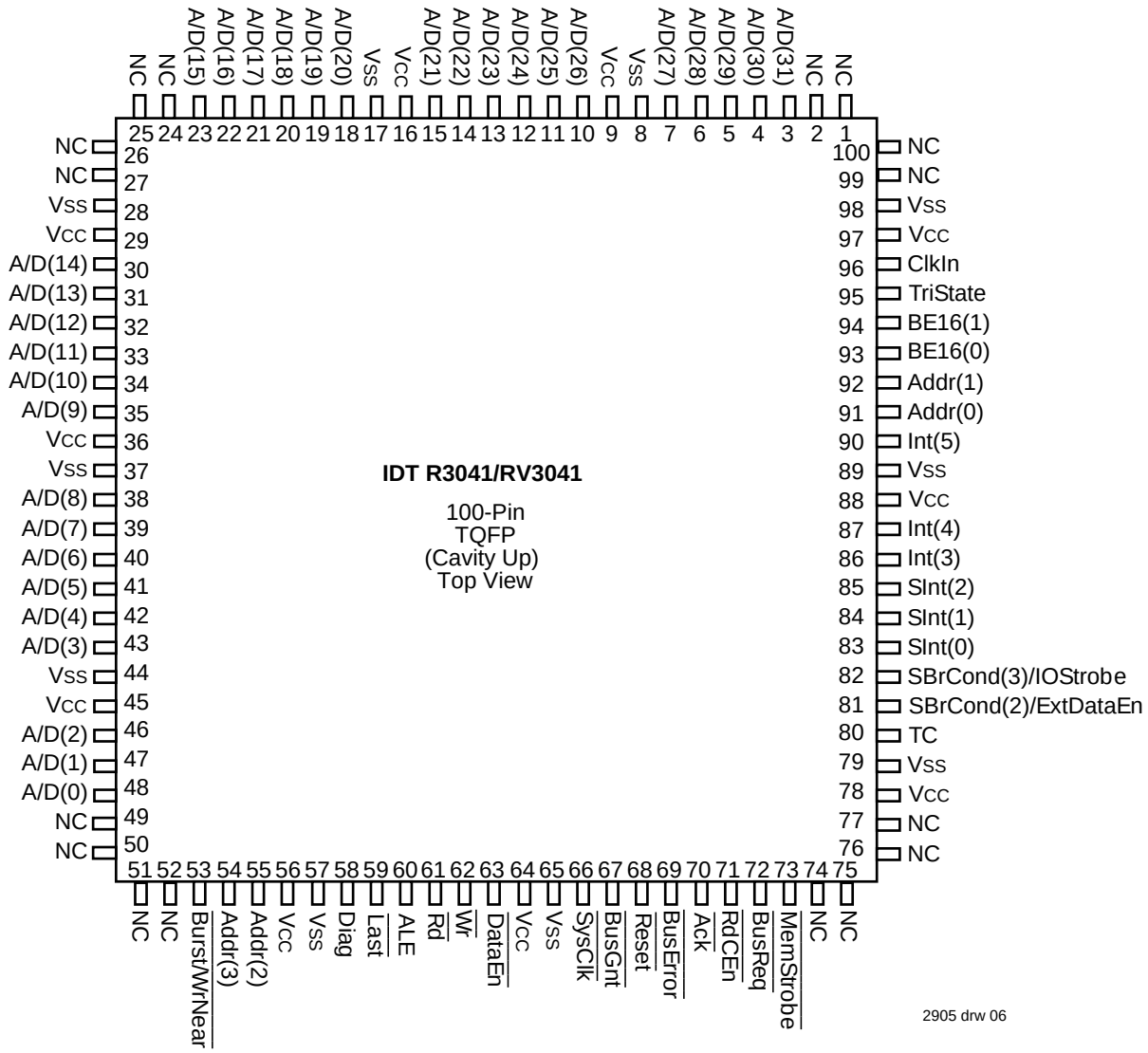


2905 drw 06

84-Pin PLCC/
Top View

(Cavity Down)

PIN CONFIGURATIONS



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PIN DESCRIPTION (Continued):

PIN NAME	I/O	DESCRIPTION
$\overline{BE16(1:0)}$	O	**Byte Enable Strobes for 16-bit Memory Port:** These active low outputs are the byte lane strobes for accesses to 16-bit wide memory ports; they are not necessarily valid for 8- or 32-bit wide ports. If $\overline{BE16(1)}$ is asserted, then the most significant byte (either D(31:24) or D(15:8), depending on system endianness) is going to be used in this transfer. If $\overline{BE16(0)}$ is asserted, the least significant byte (D(23:16) or D(7:0)) will be used. $\overline{BE16(1:0)}$ can be held inactive (masked) during read transfers, according to the programming of the CP0 Bus Control register.
	I(1)	During $\overline{Reset}$, the $\overline{BE16(1:0)}$ act as Reset Configuration Mode bit inputs for two ReservedHigh options. The $\overline{BE16(1:0)}$ output pins are designated as the unconnected Rsvd(3:2) pins in the R3051 and R3081.
$\overline{Last}$	O	**Last Datum in Mini-Burst:** This active low output indicates that this is the last datum transfer in a given transaction. It is asserted after the next to last $\overline{RdCEn}$ (reads) or $\overline{Ack}$ (writes), and is negated when $\overline{Rd}$ or $\overline{Wr}$ is negated. The $\overline{Last}$ output pin is designated in the R3051 and R3081 as the Diag(0) output pin.
$\overline{TC}$	O	**Terminal Count:** This is an active low output from the processor which indicates that the on-chip timer has reached its terminal count. It will remain low for either 1.5 clock cycles, or until software resets the timer, depending on the mode selected in the CP0 Bus Control register. Thus, the on-chip timer can function either as a free running timer for system functions such as DRAM refresh, or can operate as a software controlled time-slice timer, or real-time clock. The $\overline{TC}$ output pin is designated in the R3051 as the BrCond(1) input pin, and in the R3081 as the Run pin output.
$\overline{BusError}$	I	**Bus Error:** Input to the bus interface unit to terminate a bus transaction due to an external bus error. This signal is only sampled during read and write operations. If the bus transaction is a read operation, then the CPU will take a bus error exception.
$\overline{Int(5:3)}$ $\overline{SInt(2:0)}$	I	**Processor Interrupt:** During normal operation, these signals are logically the same as the $\overline{Int}$(5:0) signals of the R3000A. During processor reset, these signals perform mode initialization of the CPU, but in a different (simpler) fashion than the interrupt signals on the original R3000A.
	I(1)	During $\overline{Reset}$, $\overline{Int(3)}$ and $\overline{SInt(0)}$ act as Reset Configuration Mode bit inputs for the AddrDisplayAndForceCacheMiss and BigEndian options. There are two types of interrupt inputs: the $\overline{SInt}$ inputs are internally synchronized by the processor, and may be driven by an asynchronous external agent. The direct interrupt inputs are not internally synchronized, and thus must be externally synchronized to the CPU. The direct interrupt inputs have one cycle lower latency than the synchronized interrupts.
ClkIn	I	**Master Clock Input:** This is a double frequency input used to control the timing of the CPU.
$\overline{Reset}$	I	**Master Processor Reset:** This signal initializes the CPU. Reset initialization mode selection is performed during the last cycle of $\overline{Reset}$.
$\overline{TriState}$	I	**Tri-State:** This input to the R3041 requests that the R3041 tri-state all of its outputs. In addition to those outputs tri-stated during DMA, tri-state will cause $\overline{SysClk}$, $\overline{TC}$, and $\overline{BusGnt}$ to tri-state. This signal is intended for use during board testing and emulation during debug and board manufacture. The $\overline{TriState}$ input pin is designated as the unconnected Rsvd(4)pin in the R3051 and R3081.
Vcc	I	**Power:** These inputs must be supplied with the rated supply voltage (VCC). All Vcc inputs must be connected to insure proper operation.
Vss	I	**Ground:** These inputs must be connected to ground (GND). All Vss inputs must be connected to insure proper operation.

2905 tbl 05

NOTE:
1. Reset Configuration Mode bit input when $\overline{Reset}$ is asserted, normal signal function when $\overline{Reset}$ is de-asserted.

ABSOLUTE MAXIMUM RATINGS(1, 3) R3041

Symbol	Rating	Commercial	Unit
V_{TERM}	Terminal Voltage with Respect to GND	–0.5 to +7.0	V
T_C	Operating Case Temperature	0 to +85	°C
T_{BIAS}	Temperature Under Bias	–55 to +125	°C
T_{STG}	Storage Temperature	–55 to +125	°C
V_{IN}	Input Voltage	–0.5 to +7.0	V

2905 tbl 06

NOTES:
1. Stresses greater than those listed under ABSOLUTE MAXIMUM RATINGS may cause permanent damage to the device. This is a stress rating only and functional operation of the device at these or any other conditions above those indicated in the operational sections of this specification is not implied. Exposure to absolute maximum rating conditions for extended periods may affect reliability.
2. V_{IN} minimum = –3.0V for pulse width less than 15ns. V_{IN} should not exceed V_{CC} +0.5 Volts.
3. Not more than one output should be shorted at a time. Duration of the short should not exceed 30 seconds.

AC TEST CONDITIONS R3041

Symbol	Parameter	Min.	Max.	Unit
V_{IH}	Input HIGH Voltage	3.0	—	V
V_{IL}	Input LOW Voltage	—	0	V
V_{IHS}	Input HIGH Voltage	3.5	—	V
V_{ILS}	Input LOW Voltage	—	0	V

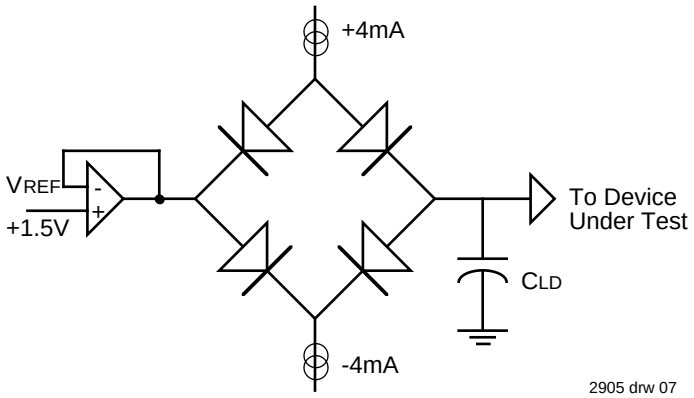
2905 tbl 08

RECOMMENDED OPERATING TEMPERATURE AND SUPPLY VOLTAGE

Grade	Temperature	GND	Vcc
Commercial	0°C to +85°C (Case)	0V	5.0 ±5%

2905 tbl 07

OUTPUT LOADING FOR AC TESTING



2905 drw 07

Signal	Cld
All Signals	25 pF

2905 tbl 09

DC ELECTRICAL CHARACTERISTICS R3041 — (T_C = 0°C to +85°C, V_{CC} = +5.0V ±5%)

Symbol	Parameter	Test Conditions	16.67MHz		20MHz		25MHz		33MHz		Unit
			Min.	Max.	Min.	Max.	Min.	Max.	Min.	Max.	
V_{OH}	Output HIGH Voltage	V_{CC} = Min., I_{OH} = –4mA	3.5	—	3.5	—	3.5	—	3.5	—	V
V_{OL}	Output LOW Voltage	V_{CC} = Min., I_{OL} = 4mA	—	0.4	—	0.4	—	0.4	—	0.4	V
V_{IH}	Input HIGH Voltage(3)	—	2.0	—	2.0	—	2.0	—	2.0	—	V
V_{IL}	Input LOW Voltage(1)	—	—	0.8	—	0.8	—	0.8	—	0.8	V
V_{IHS}	Input HIGH Voltage(2,3)	—	3.0	—	3.0	—	3.0	—	3.0	—	V
V_{ILS}	Input LOW Voltage(1,2)	—	—	0.4	—	0.4	—	0.4	—	0.4	V
C_{IN}	Input Capacitance(4)	—	—	10	—	10	—	10	—	10	pF
C_{OUT}	Output Capacitance(4)	—	—	10	—	10	—	10	—	10	pF
I_{CC}	Operating Current	V_{CC} = 5V, T_C = 25°C	—	225	—	250	—	300	—	370	mA
I_{IH}	Input HIGH Leakage	V_{IH} = VCC	—	100	—	100	—	100	—	100	µA
I_{IL}	Input LOW Leakage	V_{IL} = GND	–100	—	–100	—	–100	—	–100	—	µA
I_{OZ}	Output Tri-state Leakage	V_{OH} = 2.4V, V_{OL} = 0.5V	–100	100	–100	100	–100	100	–100	100	µA

2905 tbl 10

NOTES:
1. V_{IL} Min. = –3.0V for pulse width less than 15ns. V_{IL} should not fall below –0.5 volts for larger periods.
2. V_{IHS} and V_{ILS} apply to ClkIn and $\overline{\text{Reset}}$.
3. V_{IH} should not be held above V_{CC} + 0.5 volts.
4. Guaranteed by design.

AC ELECTRICAL CHARACTERISTICS R3041 (1, 2, 3)— (T_C = 0°C to +85°C, V_{CC} = +5.0V ±5%)

Symbol	Signals	Description	16.67MHz		20MHz		25MHz		33MHz		Unit
			Min.	Max.	Min.	Max.	Min.	Max.	Min.	Max.	
t1	$\overline{BusReq}$, $\overline{Ack}$, $\overline{BusError}$, $\overline{RdCEn}$	Set-up to $\overline{SysClk}$ rising	11	—	8	—	5.5	—	5.5	—	ns
t1a	A/D	Set-up to $\overline{SysClk}$ falling	12	—	9	—	7	—	7	—	ns
t2	$\overline{BusReq}$, $\overline{Ack}$, $\overline{BusError}$, $\overline{RdCEn}$	Hold from $\overline{SysClk}$ rising	4	—	3	—	2.5	—	2.5		ns
t2a	A/D	Hold from $\overline{SysClk}$ falling	2	—	2	—	1	—	1	—	ns
t3	A/D, Addr, Diag, ALE, $\overline{Wr}$ $\overline{Burst/WrNear}$, $\overline{Rd}$, $\overline{DataEn}$	Tri-state from SysClk rising (after driven condition)	—	13	—	10	—	10	—	10	ns
t4	A/D, Addr, Diag, ALE, $\overline{Wr}$ $\overline{Burst/WrNear}$, $\overline{Rd}$, $\overline{DataEn}$	Driven from $\overline{SysClk}$ falling (after tri-state condition)	—	13	—	10	—	10	—	10	ns
t5	$\overline{BusGnt}$	Asserted from $\overline{SysClk}$ rising	—	10	—	8	—	7	—	7	ns
t6	$\overline{BusGnt}$	Negated from $\overline{SysClk}$ falling	—	10	—	8	—	7	—	7	ns
t7	$\overline{Wr}$, $\overline{Rd}$, $\overline{Burst/WrNear}$, $\overline{TC}$	Valid from $\overline{SysClk}$ rising	—	8	—	6	—	5	—	5	ns
t7a	A/D	Valid from $\overline{SysClk}$ rising	—	12	—	9	—	8	—	8	ns
t7b	$\overline{Last}$	Valid from $\overline{SysClk}$ rising	—	12	—	9	—	8	—	8	ns
t8	ALE	Asserted from $\overline{SysClk}$ rising	—	5	—	4	—	4	—	4	ns
t9	ALE	Negated from $\overline{SysClk}$ falling	—	5	—	4	—	4	—	4	ns
t10	A/D	Hold from ALE negated	2	—	2	—	2	—	1.5		ns
t11	$\overline{DataEn}$	Asserted from $\overline{SysClk}$	—	19	—	15	—	15	—	15	ns
t12	$\overline{DataEn}$	Asserted from A/D tri-state(4)	0	—	0	—	0	—	0	—	ns
t14	A/D	Driven from $\overline{SysClk}$ rising(4)	0	—	0	—	0	—	0	—	ns
t15	$\overline{Wr}$, $\overline{Rd}$, $\overline{DataEn}$, $\overline{Burst/WrNear}$, $\overline{Last}$, $\overline{TC}$	Negated from $\overline{SysClk}$ falling	—	9	—	7	—	6	—	6	ns
t16	Addr(3:0), $\overline{BE\ 16(1:0)}$	Valid from $\overline{SysClk}$	—	11	—	8	—	7	—	7	ns
t17	Diag	Valid from $\overline{SysClk}$	—	15	—	12	—	11	—	11	ns
t18	A/D	Tri-state from $\overline{SysClk}$	—	13	—	10	—	10	—	10	ns
t19	A/D	$\overline{SysClk}$ to data out	—	16	—	13	—	12	—	12	ns
t20	ClkIn	Pulse Width High	12	—	10	—	8	—	6.5	—	ns
t21	ClkIn	Pulse Width Low	12	—	10	—	8	—	6.5	—	ns
t22	ClkIn	Clock Period	30	250	25	250	20	250	15	250	ns
t23	$\overline{Reset}$	Pulse Width from Vcc valid	200	—	200	—	200	—	200	—	µs
t24	$\overline{Reset}$	Minimum Pulse Width	32	—	32	—	32	—	32	—	sys
t25	$\overline{Reset}$	Set-up to $\overline{SysClk}$ falling	8	—	6	—	5	—	5	—	ns
t26	$\overline{Int}$	Mode set-up to $\overline{Reset}$ rising	8	—	6	—	5	—	5	—	ns
t27	$\overline{Int}$	Mode hold from $\overline{Reset}$ rising	2.5	—	2.5	—	2.5	—	2.5	—	ns
t28	$\overline{SInt}$, SBrCond	Set-up to $\overline{SysClk}$ falling	8	—	6	—	5	—	5	—	ns
t29	$\overline{SInt}$, SBrCond	Hold from $\overline{SysClk}$ falling	4	—	3	—	3	—	3	—	ns
t30	$\overline{Int}$, BrCond	Set-up to $\overline{SysClk}$ falling	8	—	6	—	5	—	5	—	ns
t31	$\overline{Int}$, BrCond	Hold from $\overline{SysClk}$ falling	4	—	3	—	3	—	3	—	ns
tsys	$\overline{SysClk}$	Pulse Width	2*t22	2*t22	2*t22	2*t22	2*t22	2*t22	2*t22	2*t22	ns
t32	$\overline{SysClk}$	Clock High Time	t22 - 2	t22 + 2	t22 - 2	t22 + 2	t22 - 2	t22 + 2	t22 - 2	t22 + 2	ns
t33	$\overline{SysClk}$	Clock Low Time	t22 - 2	t22 + 2	t22 - 2	t22 + 2	t22 - 2	t22 + 2	t22 - 2	t22 + 2	ns

2905 tbl 11

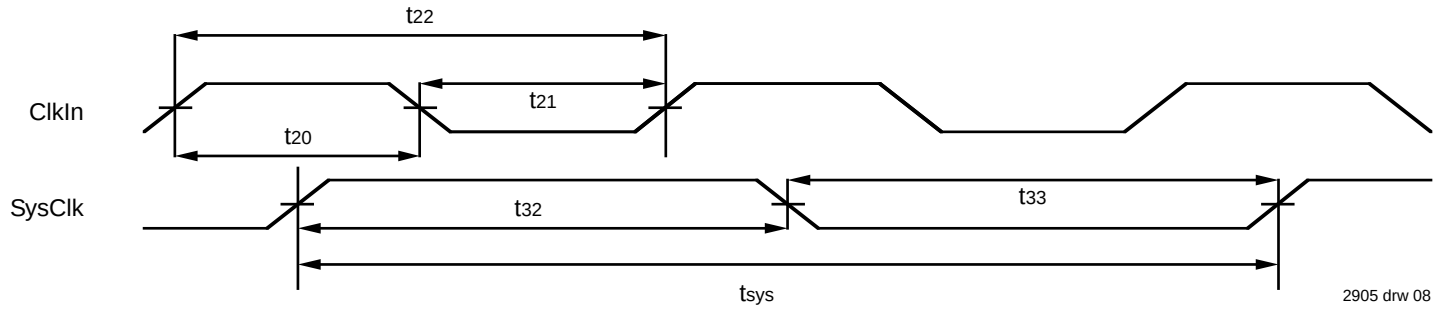


Figure 8. RISController Family Clocking

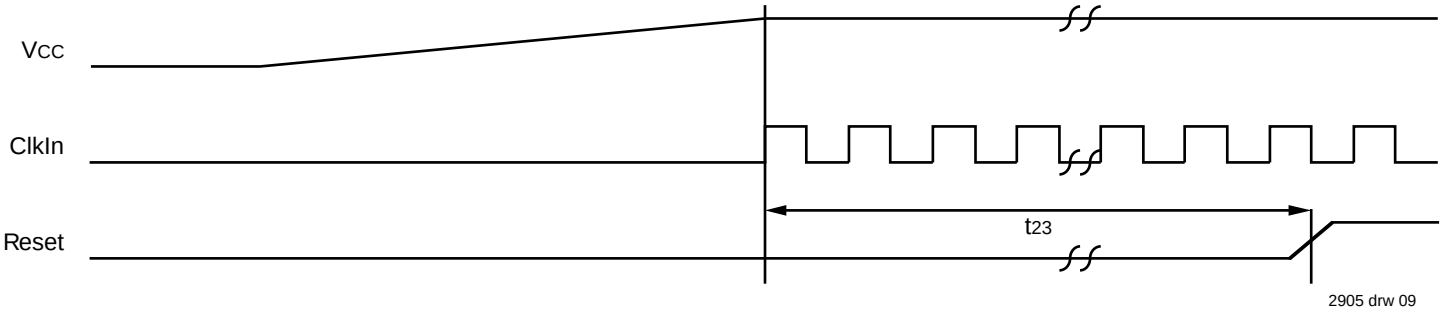


Figure 9. Power-On Reset Sequence

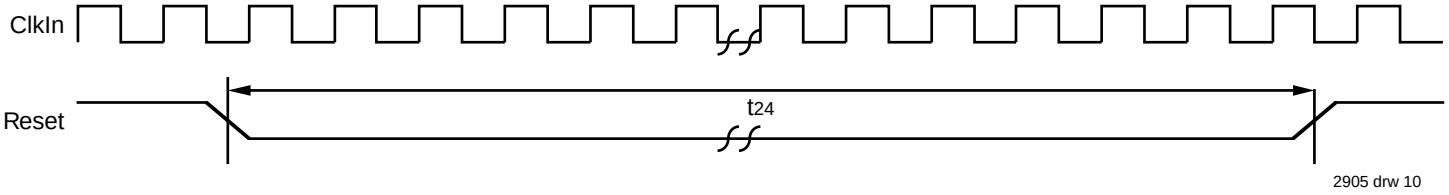


Figure 10(a). Warm Reset Sequence

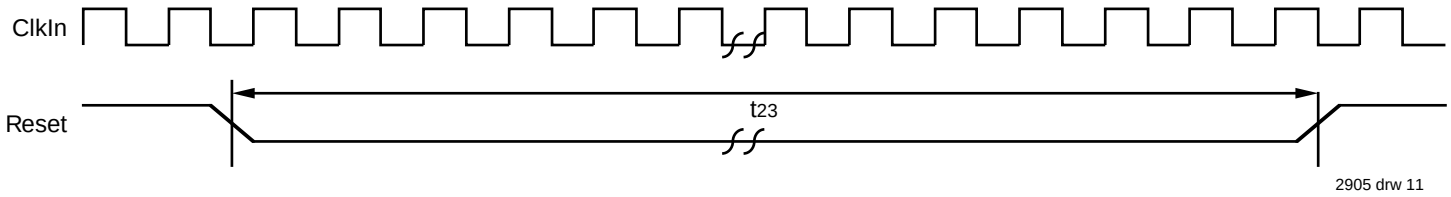


Figure 10(b). Warm Reset Sequence (Internal Pull-Ups Used)

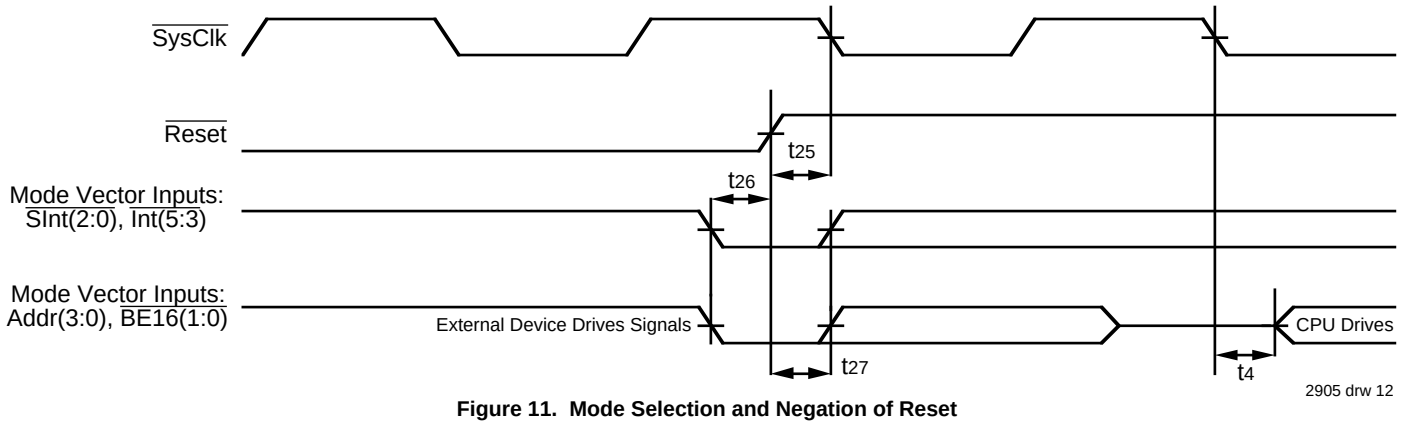


Figure 11. Mode Selection and Negation of Reset

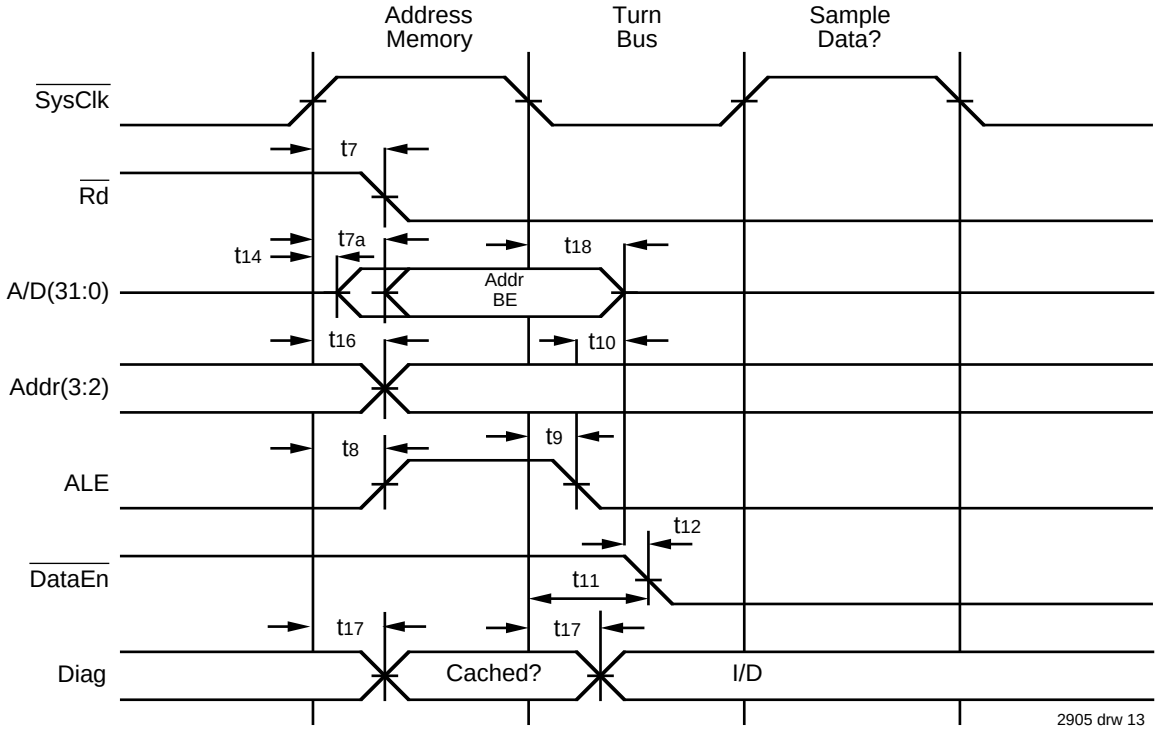


Figure 12(a). Start of Read Timing with Non-Extended Address Hold Option

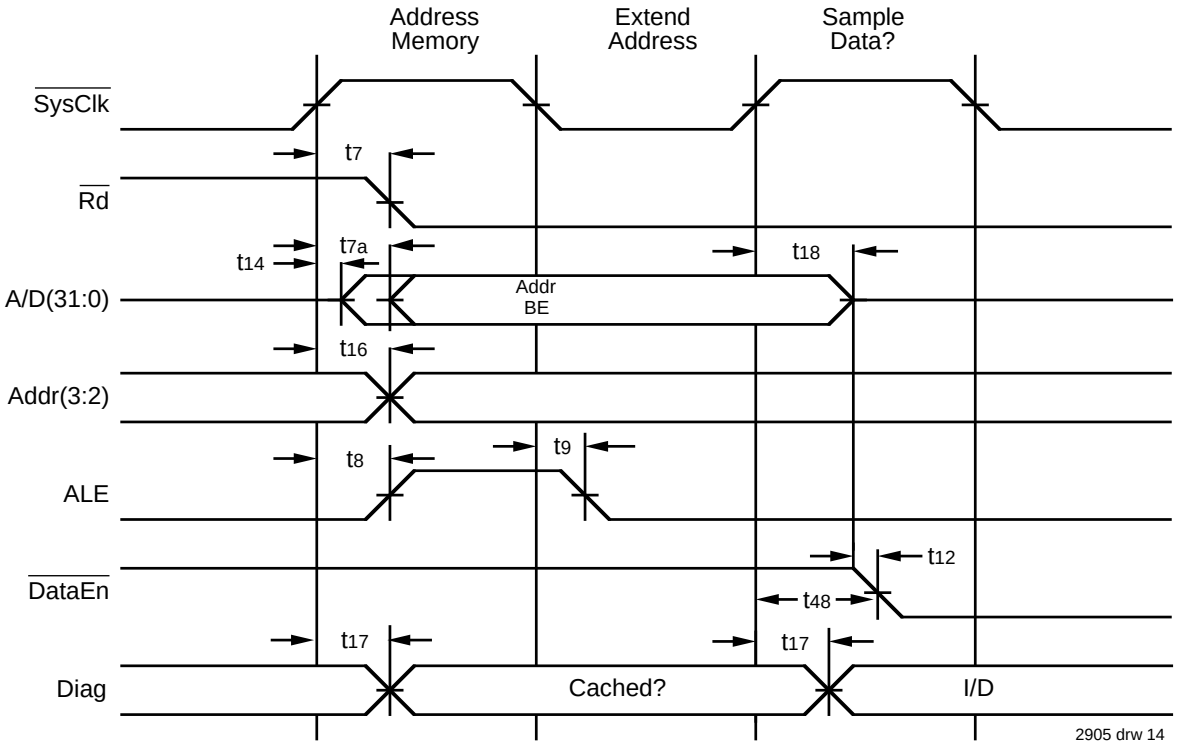


Figure 12(b). Start of Read Timing with Extended Address Hold Option

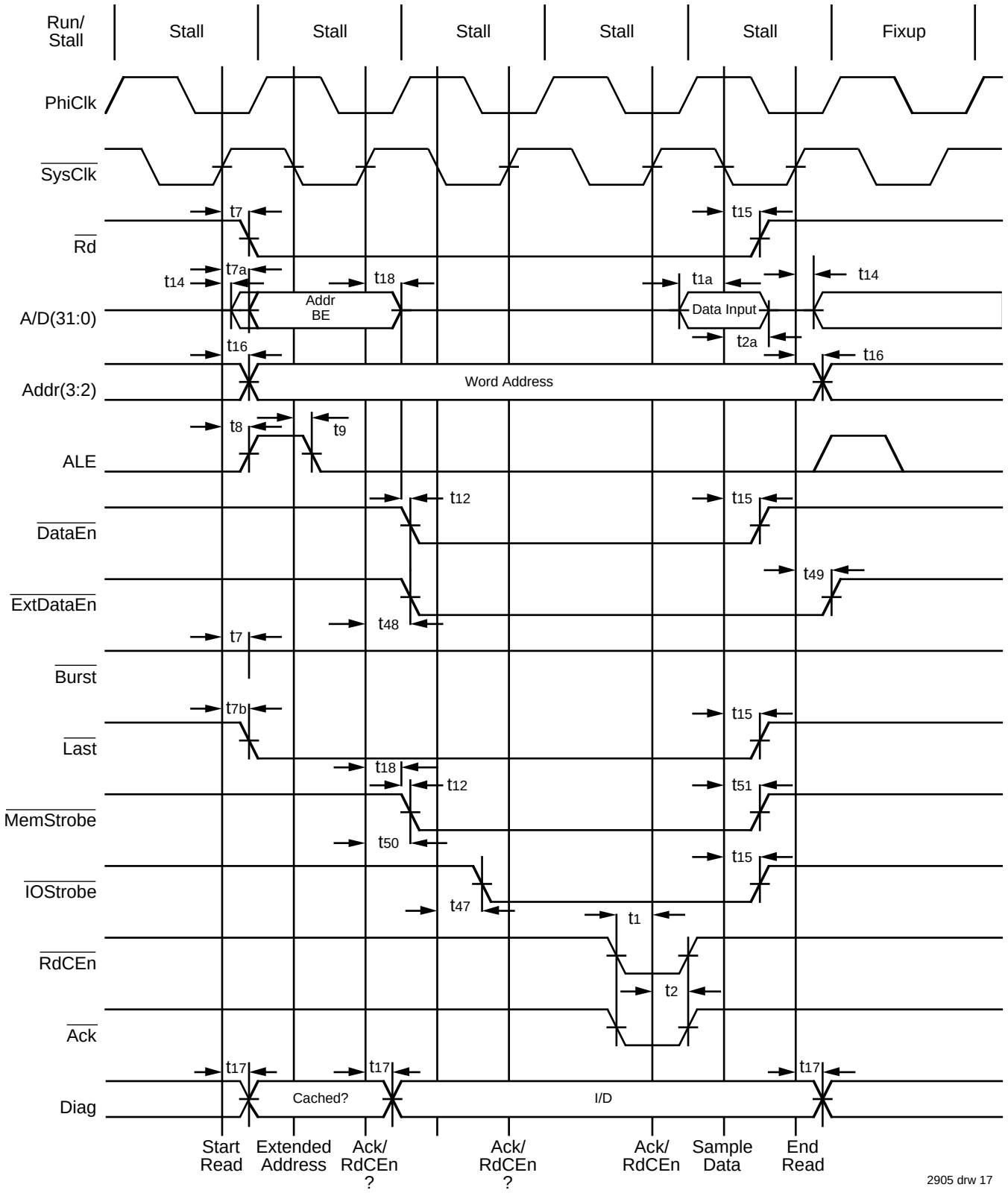


Figure 13. Single Datum Read

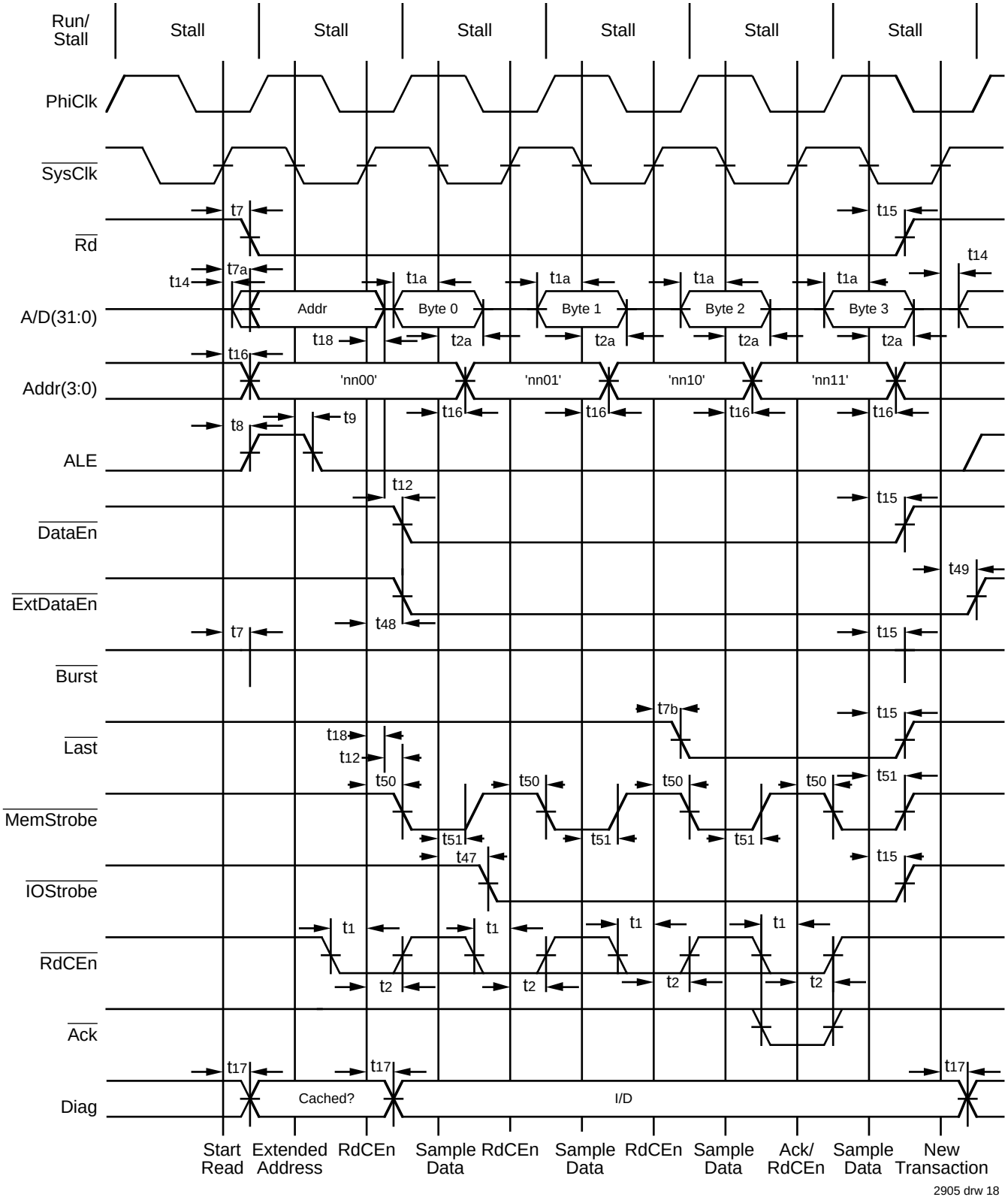


Figure 14. Mini-burst read of 32-bit datum from 8-bit wide memory port

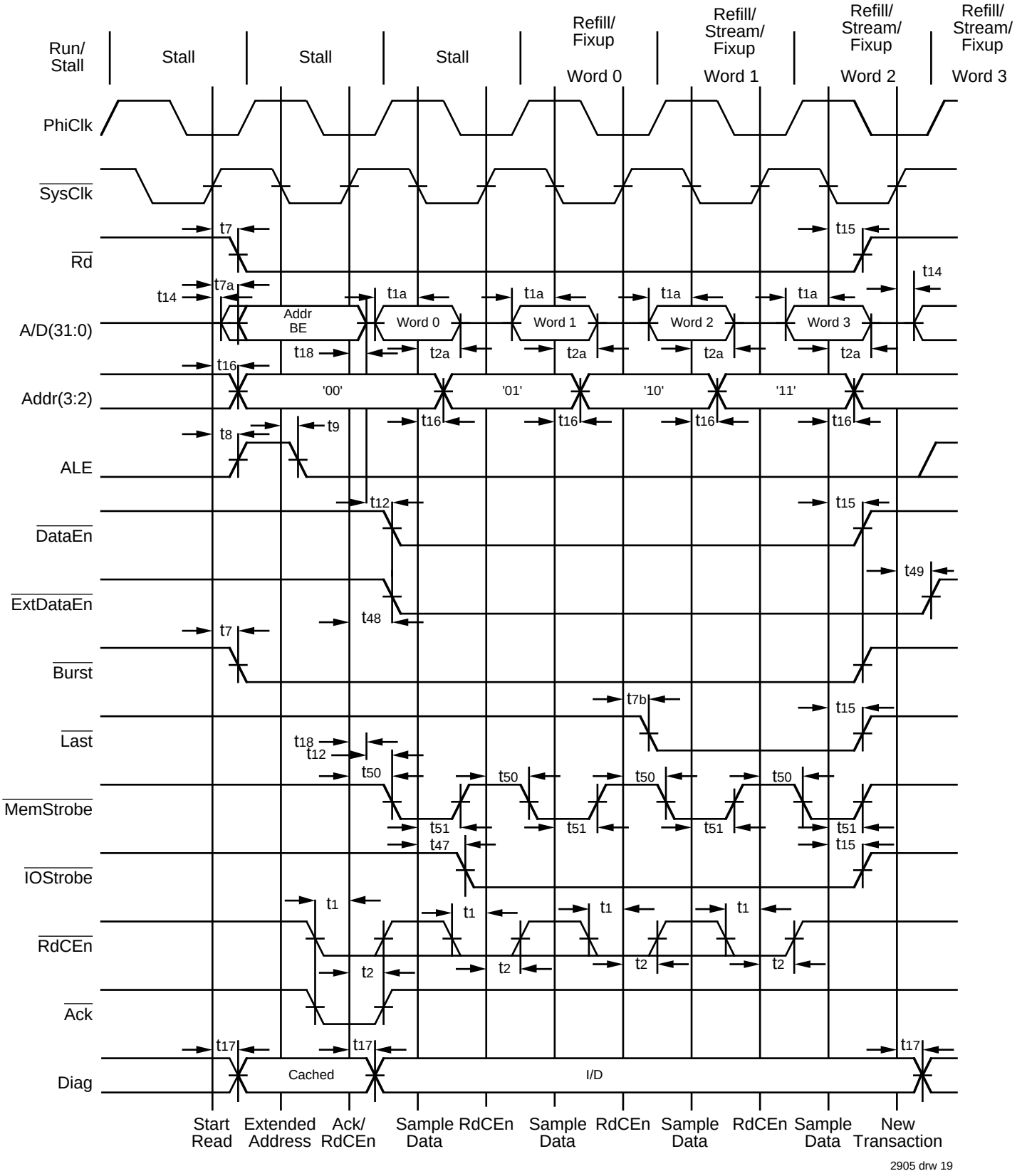


Figure 15. R3041 Quad Word Read

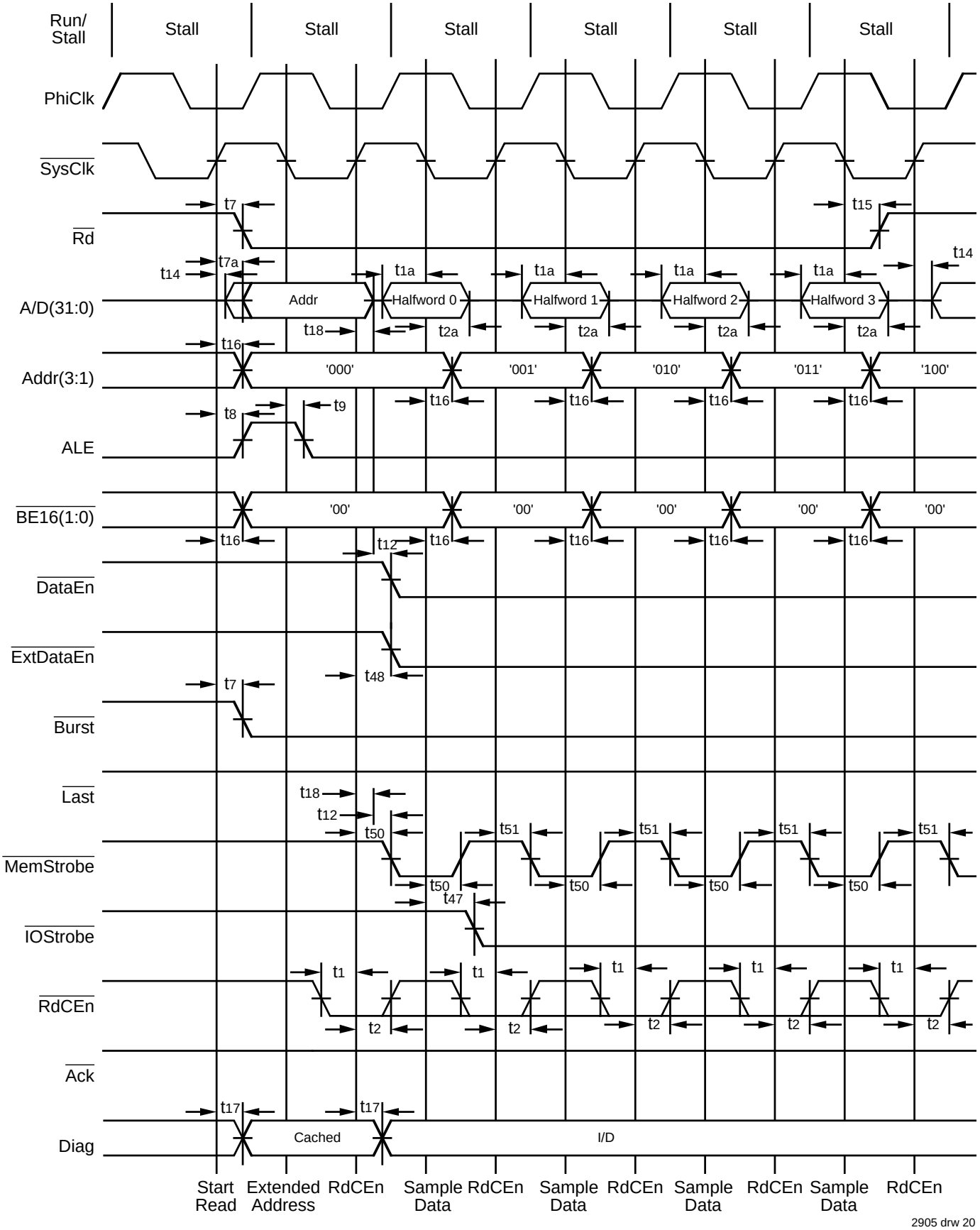


Figure 16(a). Quad Word Read to 16-bit wide Memory Port

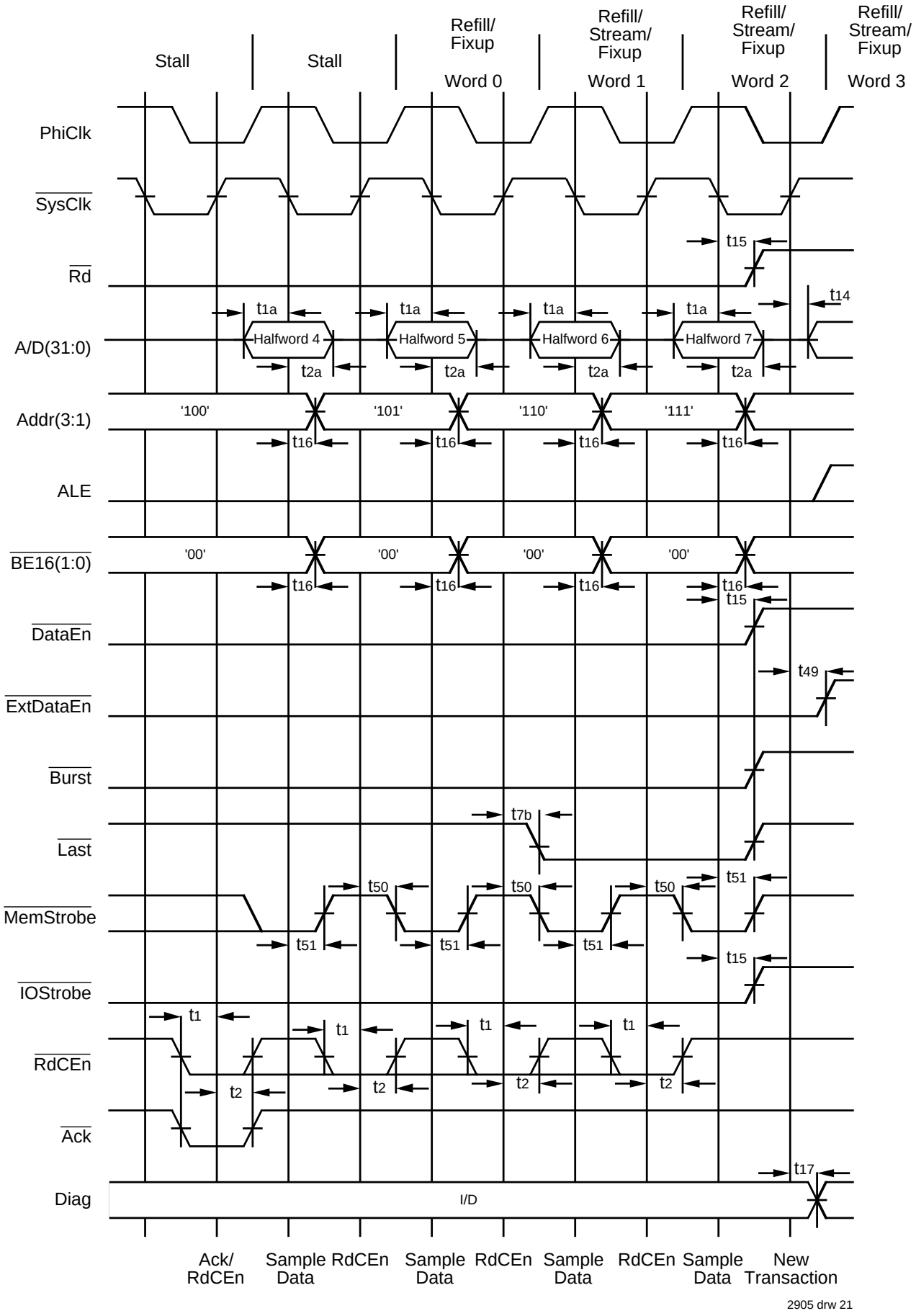


Figure 16(b). End of Quad Word read from 16-bit Wide Memory Port

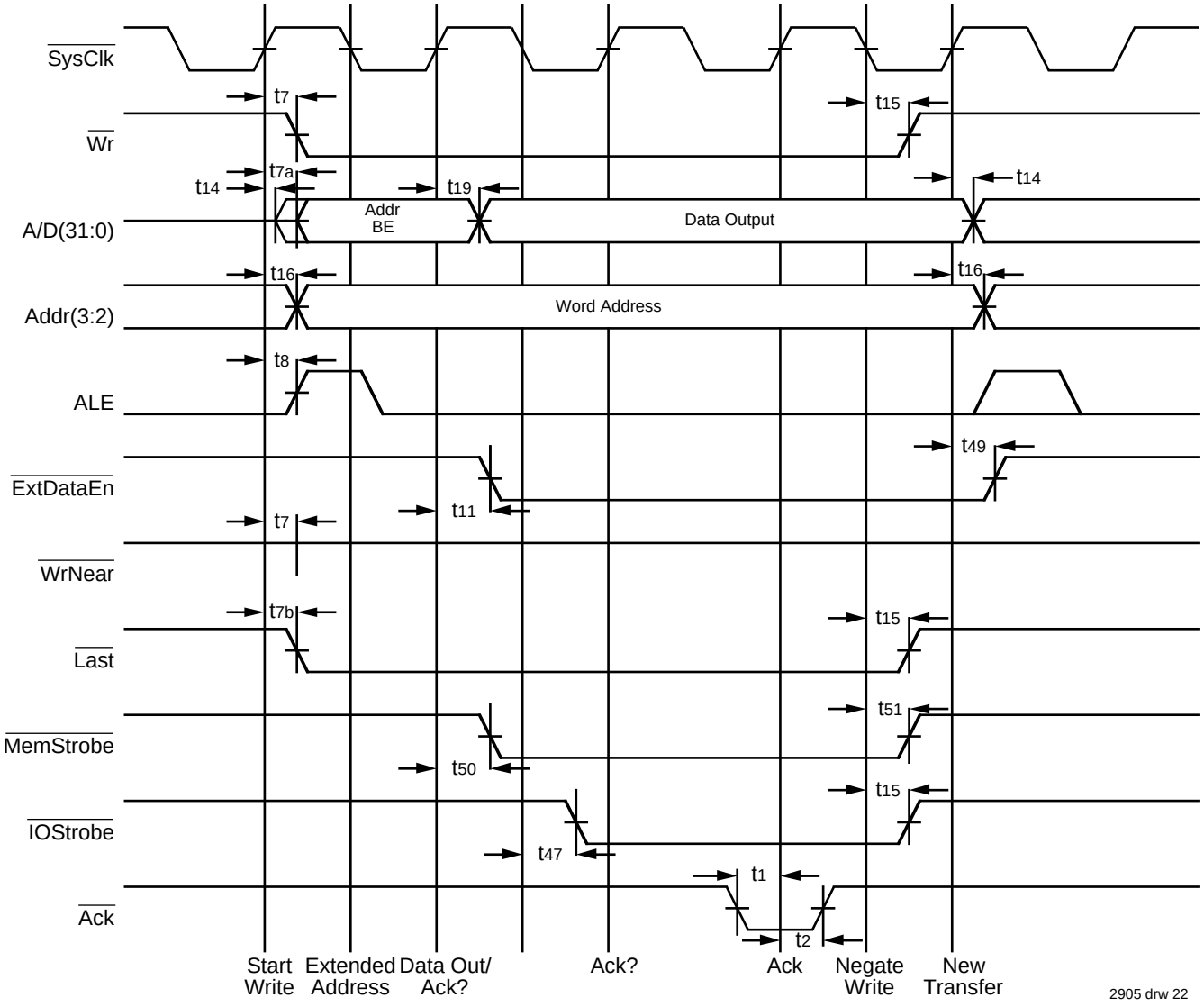


Figure 17. Basic Write to 32-bit Memory Port

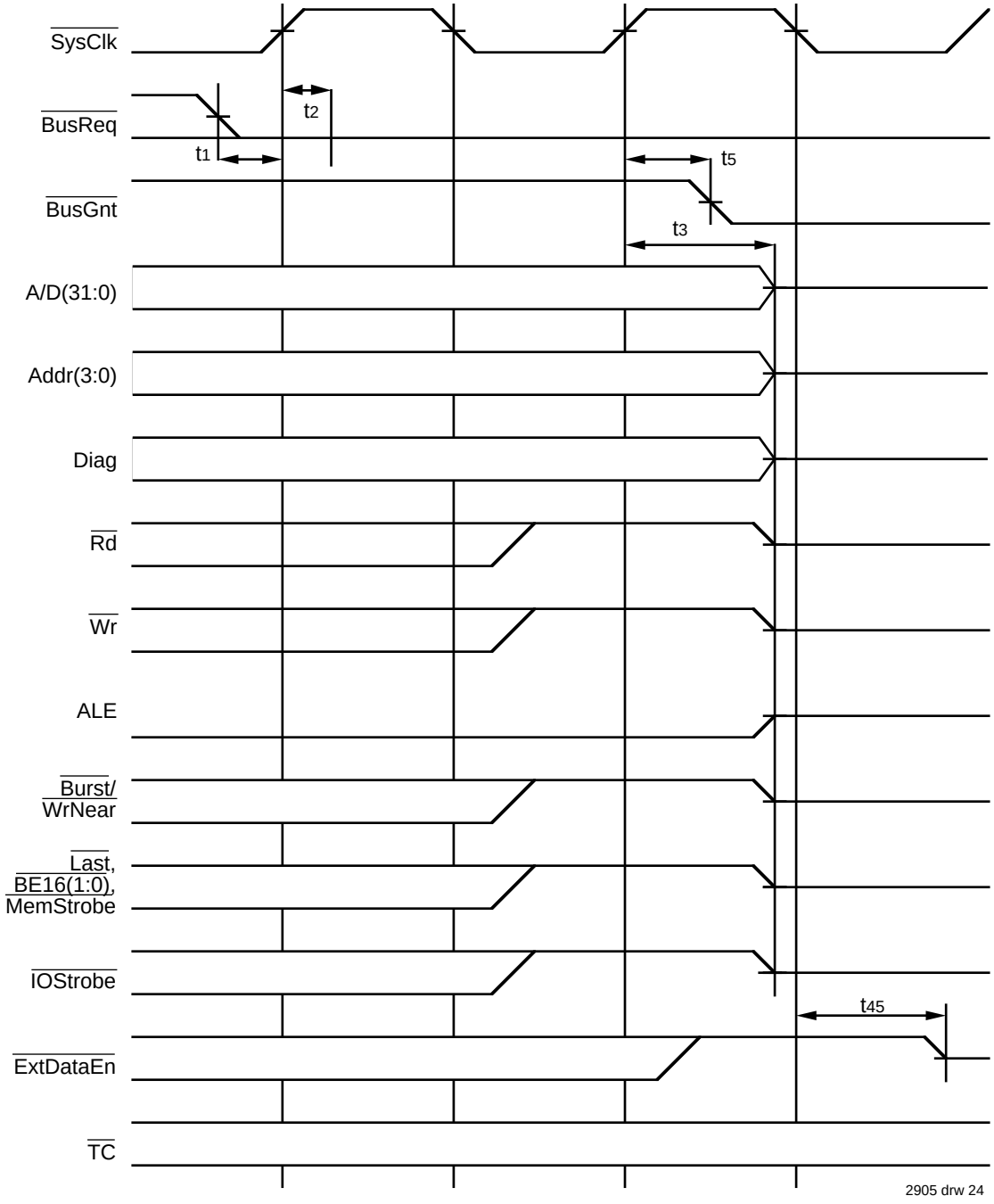


Figure 19. Request and Relinquish of R3041 Bus to External Master

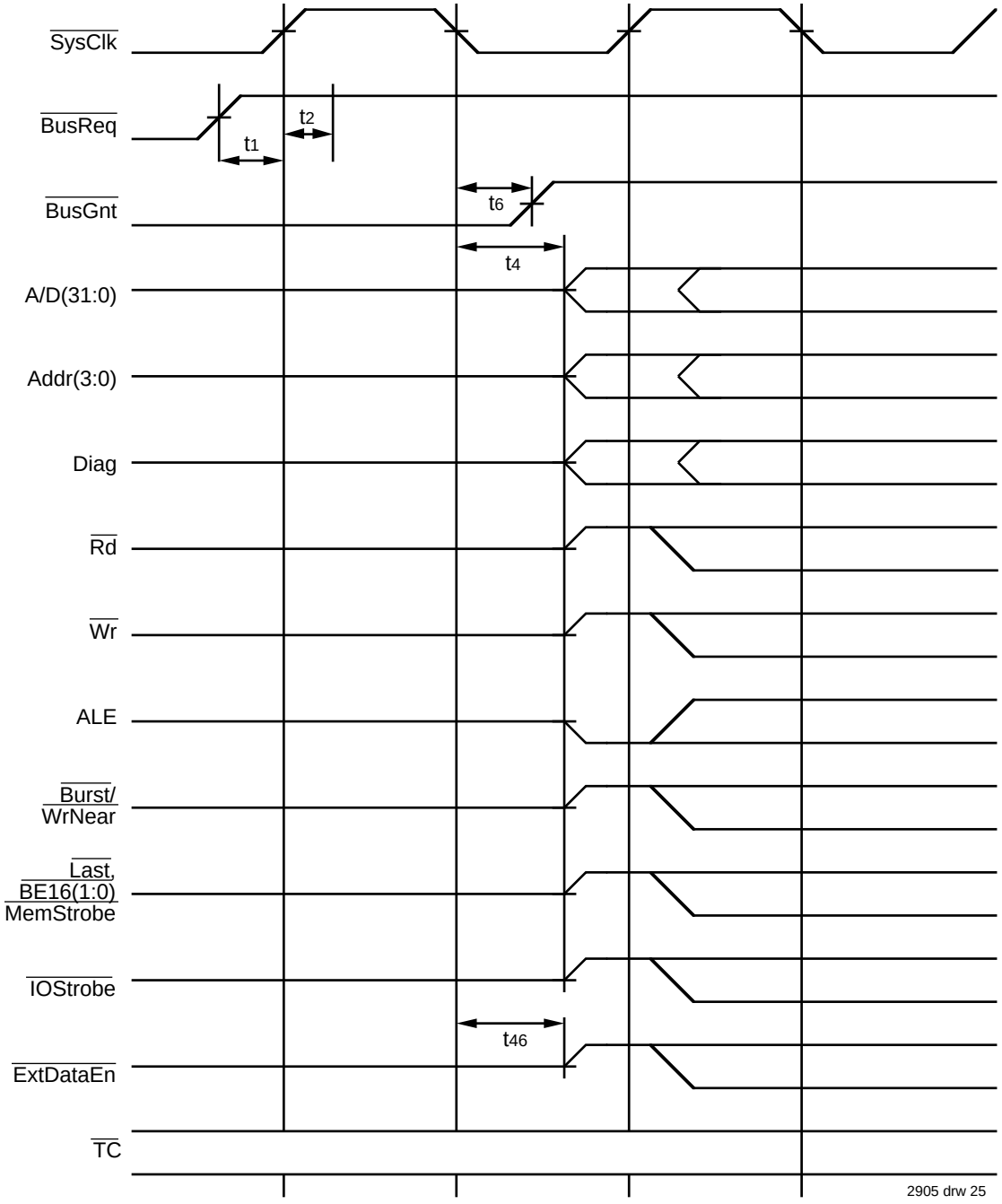


Figure 20. R3041 Regaining Bus Mastership

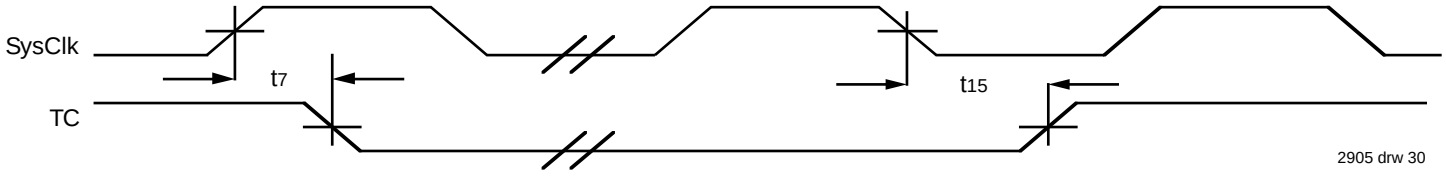
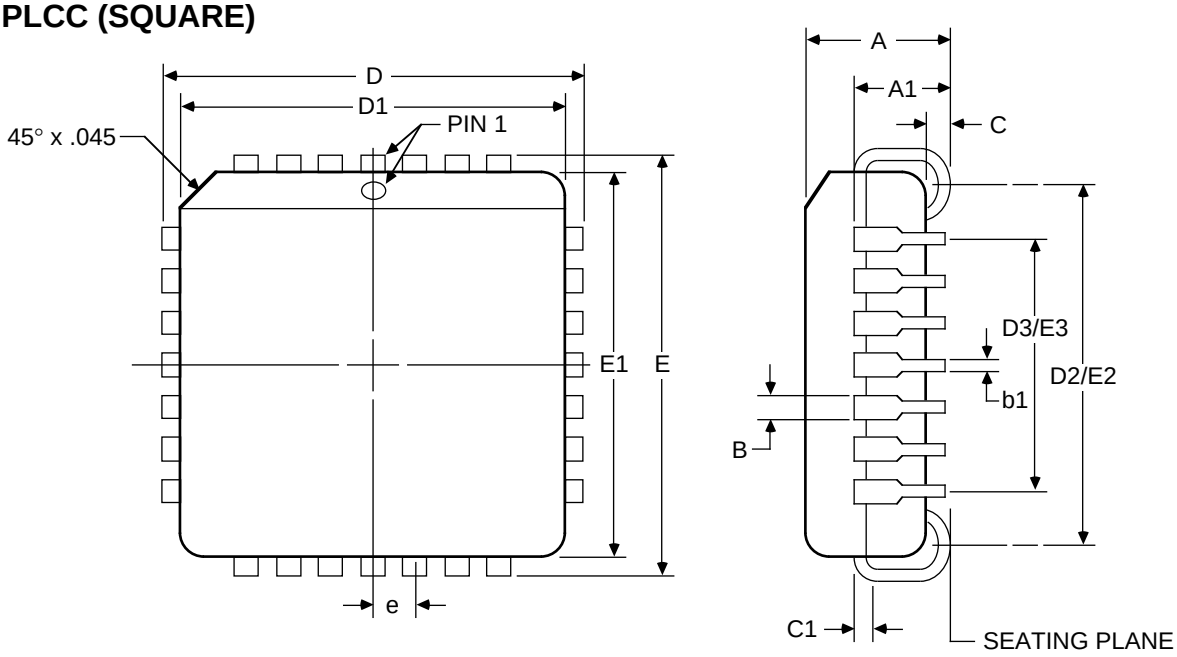


Figure 25. $\overline{TC}$ Output

84 LEAD PLCC (SQUARE)

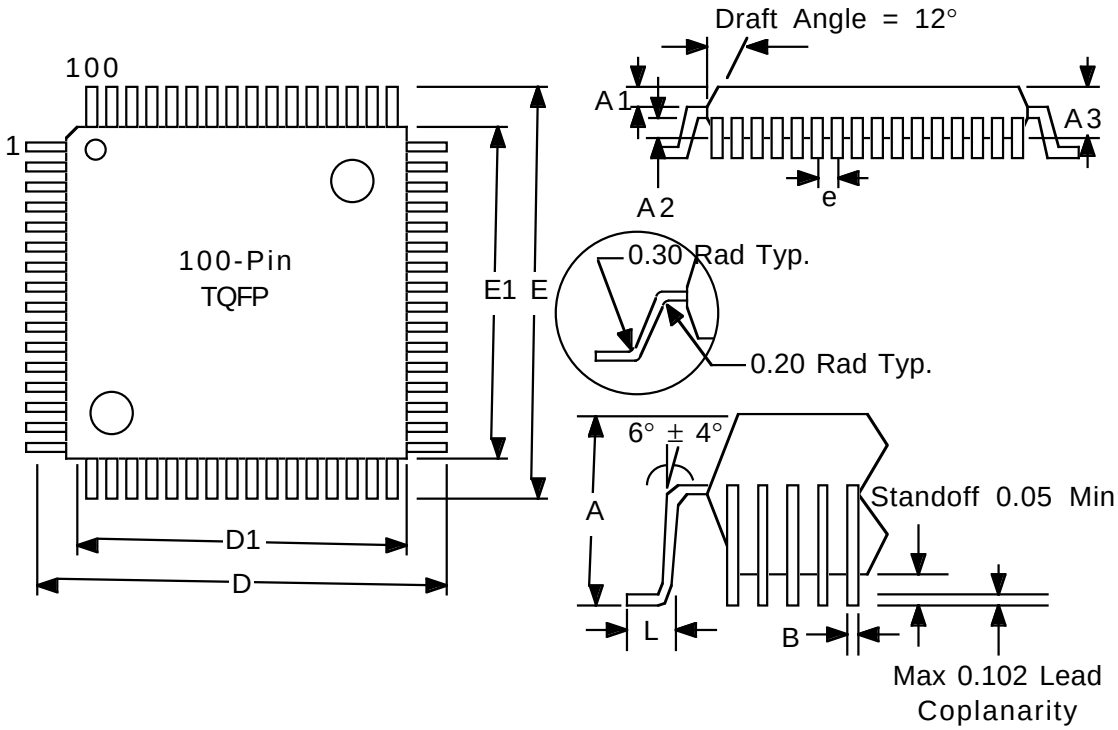


DWG #	J84-1	
# of Leads	84	
Symbol	Min.	Max.
A	165	.180
A1	.095	.115
B	.026	.032
b1	.013	.021
C	.020	.040
C1	.008	.012
D	1.185	1.195
D1	1.150	1.156
D2/E2	1.090	1.130
D3/E3	1.000 REF	
E	1.185	1.195
E1	1.150	1.156
e	.050 BSC	
ND/NE	21	

2905 tbl 13

NOTES:
1. All dimensions are in inches, unless otherwise noted.
2. BSC—Basic lead Spacing between Centers.
3. D & E do not include mold flash or protutions.
4. Formed leads shall be planar with respect to one another and within .004" at the seating plane.
5. ND & NE represent the number of leads in the D & E directions respectively.
6. D1 & E1 should be measured from the bottom of the package.
7. PLCC is pin & form compatible with MQUAD; the MQUAD package is used in other RISController family members.

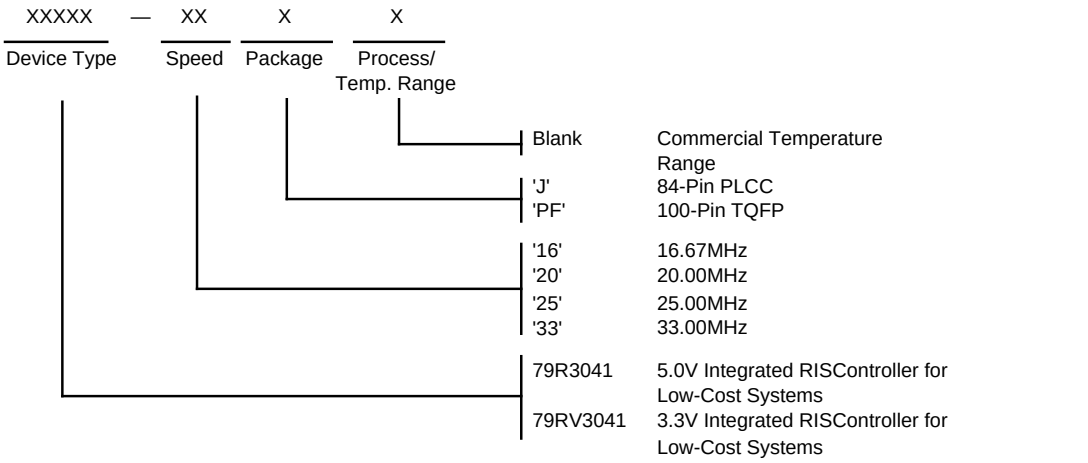
100-PIN TQFP



DWG #	TQFP	
# of Leads	100	
Symbol	Min.	Max.
A	—	1.60
A1	0.5	0.15
A2	1.35	1.45
D	15.75	16.25
D1	13.95	14.05
E	15.75	16.25
E1	13.95	14.05
L	0.45	0.70
N	100	
e	0.50BSC	
b	0.17	0.27
ccc	—	0.08
ddd	—	0.08
R	0.08	0.20
R1	0.08	—
θ	0	7.0
θ1	11.0	13.0
θ2	11.0	13.0
c	0.09	0.16

2905 tbl 14

ORDERING INFORMATION



2905 drw 32

VALID COMBINATIONS

79R3041 - 16	TQFP, PLCC Package
79R3041 - 20	TQFP, PLCC Package
79R3041 - 25	TQFP, PLCC Package
79R3041 - 33	PLCC Package Only
79RV3041 - 16	TQFP, PLCC Package
79RV3041 - 20	TQFP, PLCC Package
79RV3041 - 25	TQFP, PLCC Package
79RV3041 - 33	TQFP, PLCC Package